Lead Free Flux Cored Wire Solder

FLUX CORED WIRE SOLDER

STG

Flux ultra-low spattering type

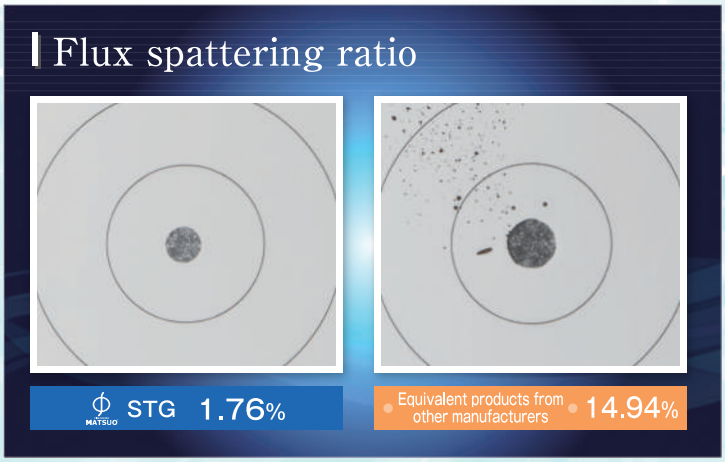
Significant reduction in flux spattering.
Also has the feature of preventing flux residue cracking or peeling off.

Fine Solder

Product Features

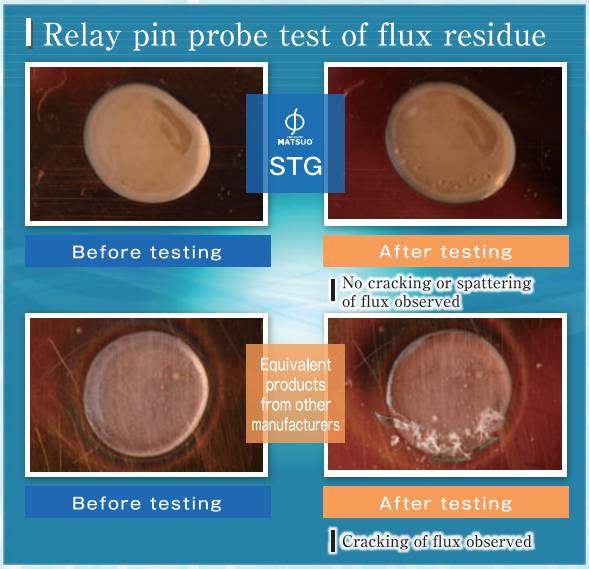
Achieving ultra low flux spattering

Adoption of the special flux, which is viscous itself, contributes to significant reduction in flux spattering during soldering, achieving ultra low flux spattering.



Prevention of cracks in flux residue

Designed to reduce potential for cracking of flux residue, not just at room temperature, but at high temperatures (85℃) and low temperatures (-15℃). Suitable for soldering bent or movable parts.



Alloy no.	JIS mark	Alloy composition	Solidus temperature	Liquidus temperature	Wire diameter (mm)
FLF01	A30C5	Sn96.5%-Ag3.0%-Cu0.5%	Approx. 217℃	Approx. 219℃	φ0.3·φ0.4·φ0.5 φ0.6·φ0.8·φ1.0 φ1.2·φ1.6·φ2.0
FLF07	C7A3	Sn99.0%-Ag0.3%-Cu0.7%	Approx. 217℃	Approx. 226℃	
FLF03	C7	Sn99.3%-Cu0.7%	Approx. 227℃	Approx. 227℃	

Items	STG	Specifications (Reference) JIS Z 3283/AA grade
Alloy composition	FLF01/FLF03/FLF07	———
Flux content	3%	2.7% ~ 3.3%
Halide content	0.01%	0.1% >
Aqueous solution resistance	1,200Ωm	> 1,000Ωm
Insulation resistance test (85℃ 85%RH 168hr)	> $2\times10^{9}\Omega$	> $1\times10^{9}\Omega$
Migration test (85℃ 85%RH 1,000hr)	Pass	No migration
Spread rate	70%	> 65%

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